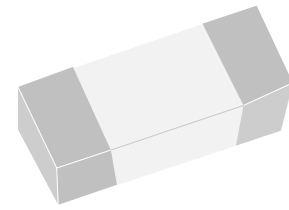


## Time Delay SMD Fuses 2410BC-TD Series

### Descriptions

Chip Fuse devices are set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

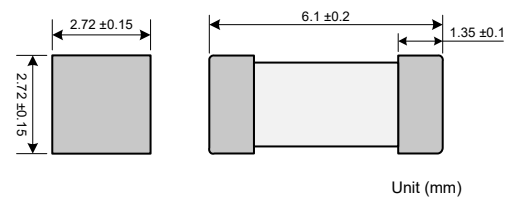
2410BC-TD SMD fuses for the small size and good electrical performance, reliability and quality.



**Top View (2410BC-TD)**

Electrical Characteristics		
Rated Current	1.0In	2.0In
0.5-7A	4 hour min	60 sec max

### Product Dimensions

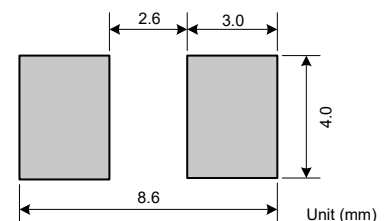


Unit (mm)

### Features

- Time delay surface mount fuses
- Compatible with reflow and wave soldering
- Excellent environmental integrity
- One time positive disconnect
- RoHS compliant

### Recommended land pattern



Unit (mm)

### Electrical information (Tamb=25°C)

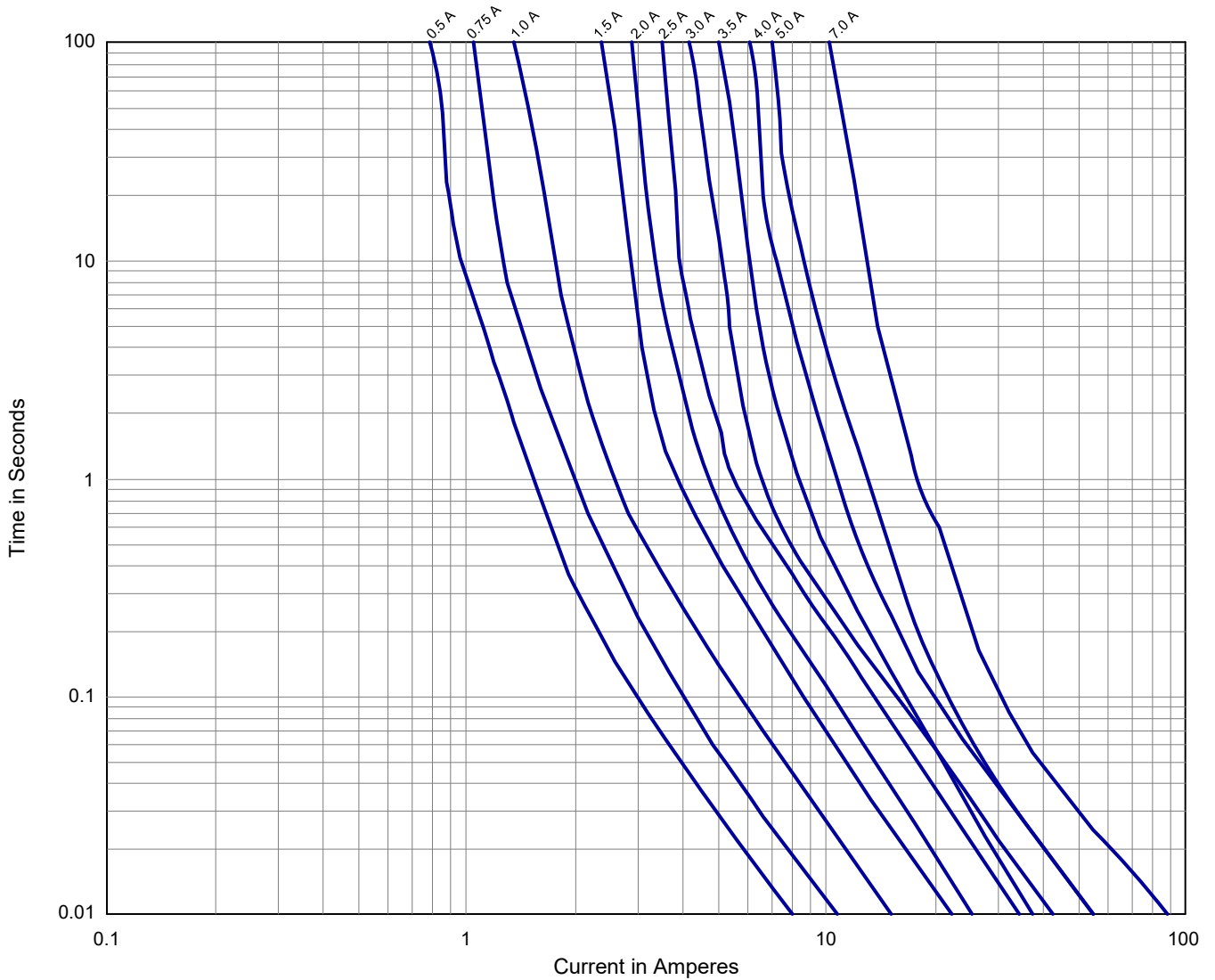
Part number	Rated Voltage (V)		Rated Current (A)	Breaking Capacity * (A)		Typical Cold Resistance * (mΩ)	Typical Voltage Drop (mV)	Typical Pre-arcing I <sup>2</sup> t * (A <sup>2</sup> Sec)
	AC	DC		@250VAC	@60VDC			
2410BC125-0050TD	125	60	0.50	50	50	400	250	0.72
2410BC125-0075TD	125	60	0.75	50	50	230	250	1
2410BC125-0100TD	125	60	1.00	50	50	160	256	2.5
2410BC125-0150TD	125	60	1.50	50	50	65	125	2.2
2410BC125-0200TD	125	60	2.00	50	50	48	130	9
2410BC125-0250TD	125	60	2.50	50	50	36	130	16
2410BC125-0300TD	125	60	3.00	50	50	25	100	15
2410BC125-0350TD	125	60	3.50	50	50	20	95	14
2410BC125-0400TD	125	60	4.00	50	50	19	105	38
2410BC125-0500TD	125	60	5.00	50	50	13.5	100	34
2410BC125-0700TD	125	60	7.00	50	50	8.9	100	90

\* AC Interrupting Rating (measured at designated voltage, 100% power factor)

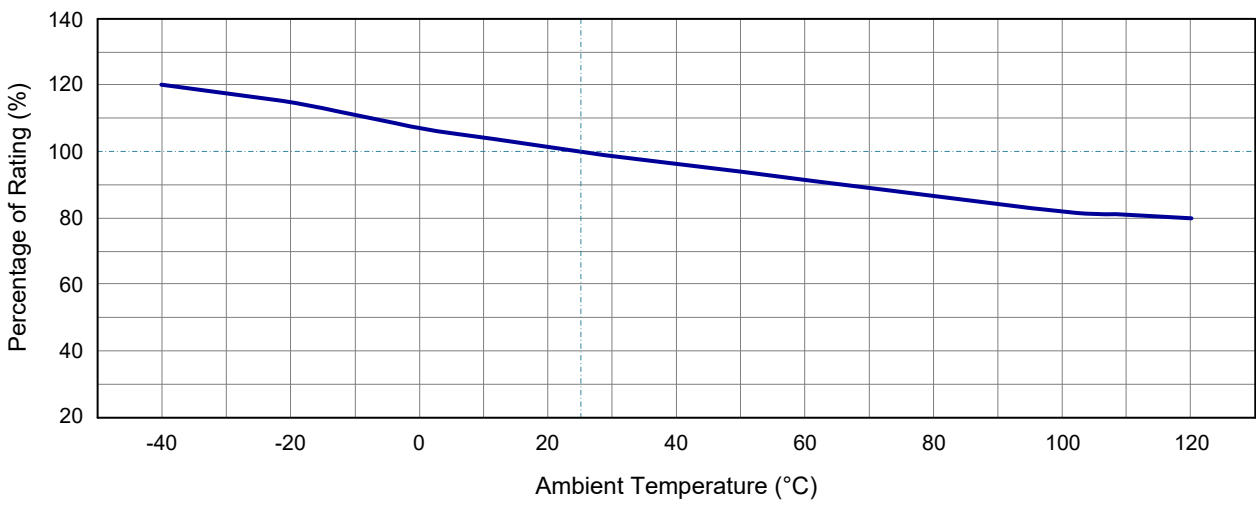
\* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 °C

\* Typical Melting I<sup>2</sup>t (Measured with a battery bank at Rated DC voltage, 10x-rated current, but not exceeding the interrupting rating, time constant of calibrated circuit less than 50 microseconds)

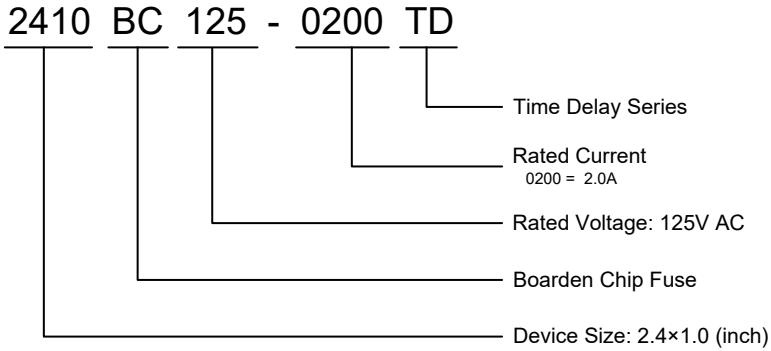
**Time-Current Curves**



**Temperature Derating Curve**



**Part Numbering System**

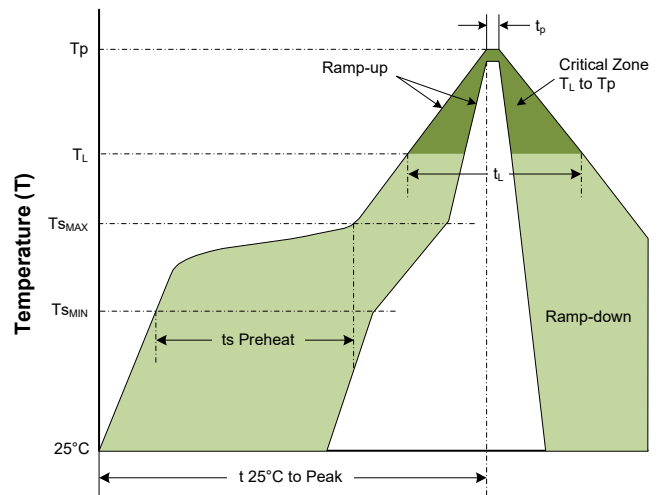


**Order Information**

Device	Quantity	Reel Size
2410BC-TD Series	5000 pcs	13 Inch

**Soldering Parameters**

Profile Feature	Lead-Free Assembly
Average Ramp-up Rate ( $T_{S_{MAX}}$ to $T_p$ ) Average Ramp-down Rate ( $T_p$ to $T_L$ )	3°C/second max. 6°C/second max.
<b>Preheat</b> • Temperature Min ( $T_{S_{MIN}}$ ) • Temperature Max ( $T_{S_{MAX}}$ ) • Time ( $t_s$ Preheat)	150°C 200°C 60-180 seconds
<b>Time maintained above:</b> • Temperature ( $T_L$ ) • Time ( $t_L$ )	217°C 60-150 seconds
<b>Peak/Classification Temperature</b> • Temperature ( $T_p$ )	260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual Peak</b> Time ( $t_p$ )	20-40 seconds
<b>Time 25°C to peak Temperature</b>	8 minutes max
<b>Do not exceed</b>	280 °C



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